

# BRMJD350Q

Rev.A Oct.-2023

## 描述 / Descriptions

TO-252 塑封封装 PNP 半导体三极管。

Silicon PNP transistor in a TO-252 Plastic Package.

## 特征 / Features

耐压高，符合 AEC-Q101 标准高可靠性要求，无卤产品。

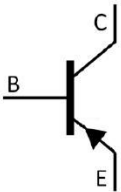
High voltage, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

## 用途 / Applications

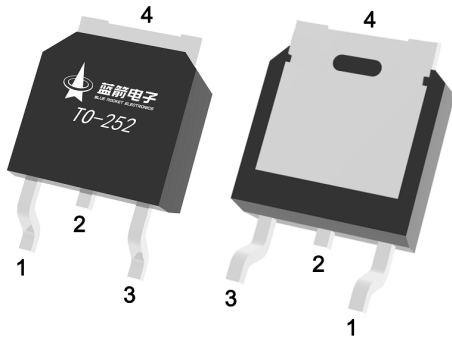
用于一般高压电路，满足汽车应用的严格要求。

High voltage general purpose applications, Meet the stringent requirements of automotive applications.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



PIN1 : Base

PIN 2,4 : Collector

PIN 3 : Emitter

## 放大及印章代码 / hFE Classifications & Marking

见印章说明。

See Marking Instructions.

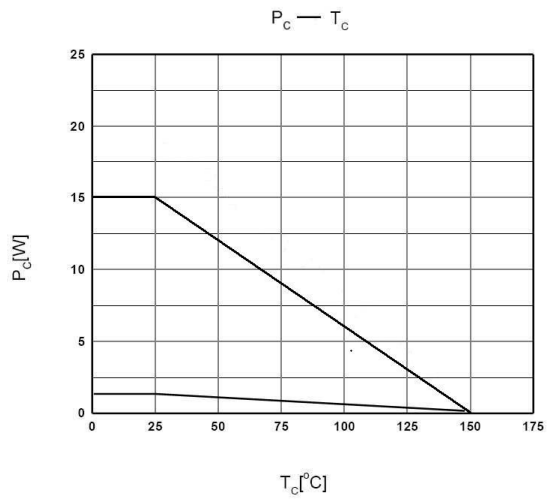
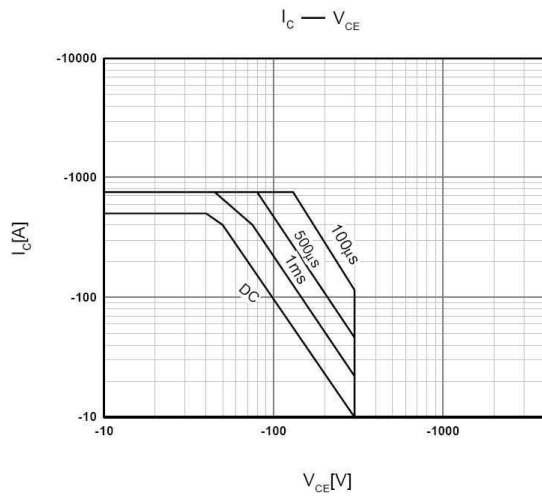
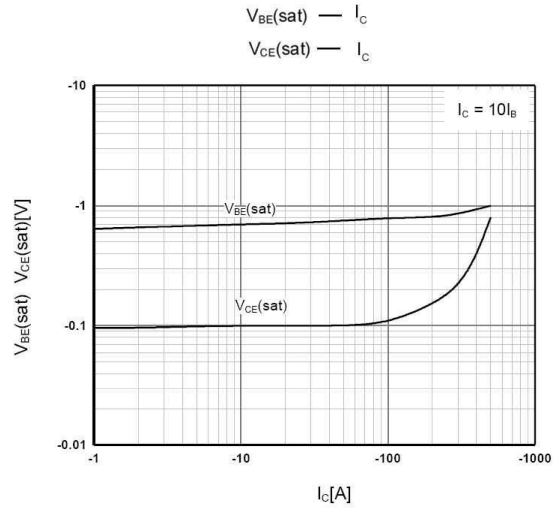
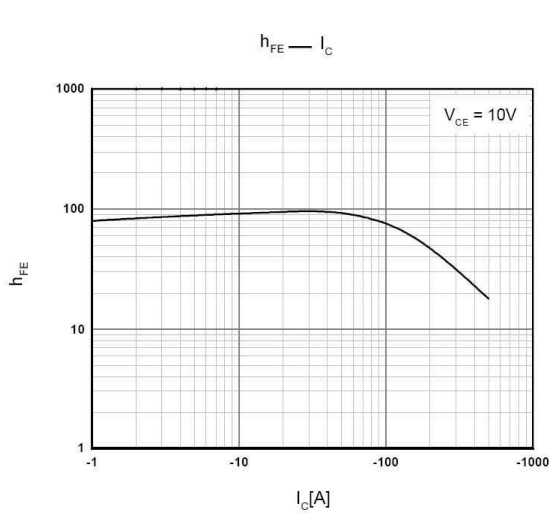
**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V <sub>CB0</sub>	-300	V
Collector to Emitter Voltage	V <sub>CEO</sub>	-300	V
Emitter to Base Voltage	V <sub>EBO</sub>	-5	V
Collector Current - Continuous	I <sub>C</sub>	-500	mA
Collector Power Dissipation	P <sub>C</sub>	1.56	W
Collector Power Dissipation	P <sub>C</sub> (T <sub>C</sub> =25°C)	15	W
Junction Temperature	T <sub>j</sub>	150	°C
Storage Temperature Range	T <sub>stg</sub>	-55~150	°C

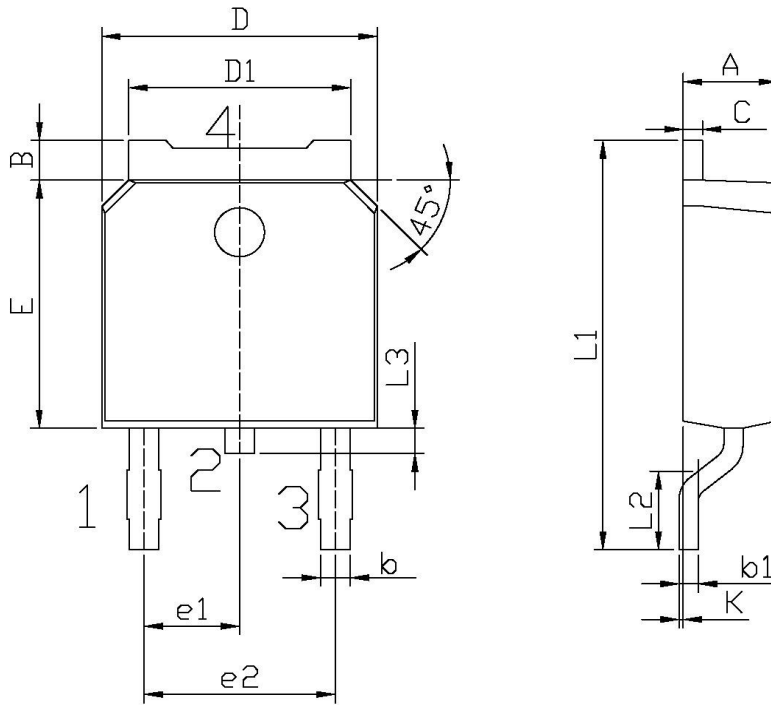
**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	V <sub>CB0</sub>	I <sub>C</sub> =-0.1mA I <sub>E</sub> =0	-300			V
Collector to Emitter Breakdown Voltage	V <sub>CEO</sub>	I <sub>C</sub> =-1mA I <sub>B</sub> =0	-300			V
Emitter to Base Breakdown Voltage	V <sub>EBO</sub>	I <sub>C</sub> =-0.1mA I <sub>B</sub> =0	-5			V
Collector Cut-Off Current	I <sub>CB0</sub>	V <sub>CB</sub> =-300V I <sub>E</sub> =0			-100	μA
Emitter Cut-Off Current	I <sub>EBO</sub>	V <sub>EB</sub> =-3V I <sub>C</sub> =0			-100	μA
DC Current Gain	h <sub>FE</sub>	V <sub>CE</sub> =-10V I <sub>C</sub> =-50mA	30		240	

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

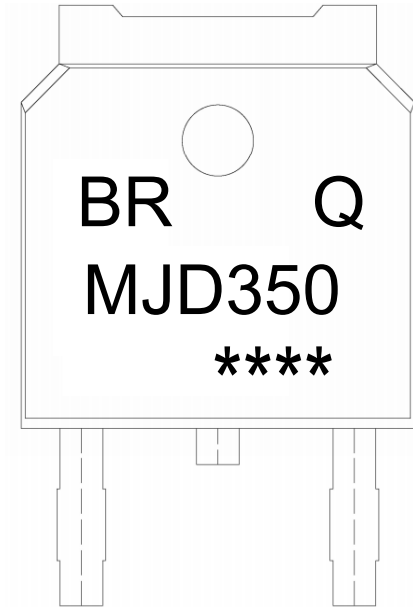


单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.70	0.90	e2	4.43	4.73
b1	0.45	0.55	L1	9.85	10.35
C	0.45	0.55	L2	1.70	2.00
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

TO-252

**印章说明 / Marking Instructions**



说明：

BR： 为公司代码

Q： 为汽车无卤产品标识

MJD350： 为产品型号

\*\*\*\*： 为生产批号代码，随生产批号变化

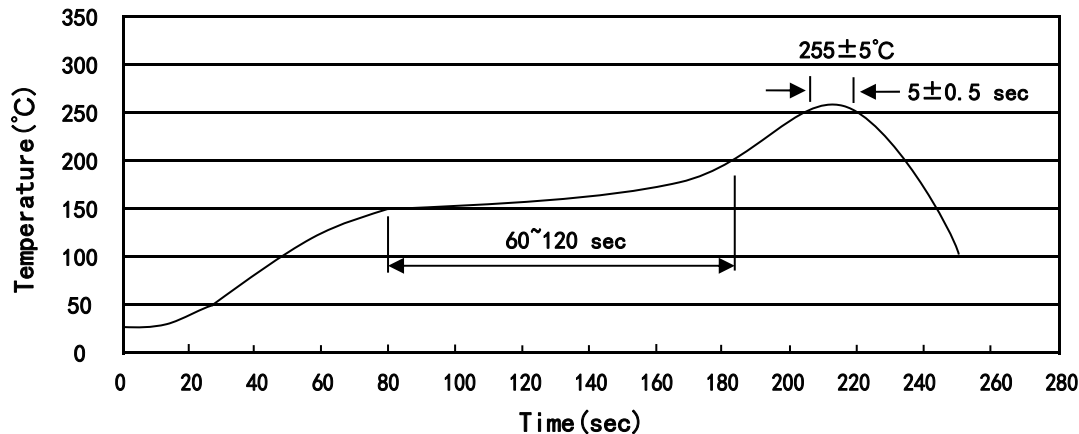
Note:

BR: Company Code

Q: Automobile halogen-free product Code

MJD350: Product Type

\*\*\*\*: Lot No. Code, code change with Lot No

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


说明：

1. 预热温度 150~200°C，时间 60~120sec;
2. 峰值温度 255±5°C，时间持续为 5±0.5sec;
3. 焊接制程冷却速度为 2~10°C/sec.

Note:

1. Preheating: 150~200°C, Time: 60~120sec.
2. Peak Temp.: 255±5°C, Duration: 5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.: 260±5°C

Time: 10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
TO-252	2,500	2	5,000	6	30,000	13" × 16	360×360×50	380×335×366

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-251/252	75	48	3,600	5	18,000	526×20.5×5.25	555×164×50	575×290×180

**使用说明 / Notices**